



IMPORTANT NOTICE

10 December 2015

1. Global joint venture starts operations as WeEn Semiconductors

Dear customer,

As from November 9th, 2015 NXP Semiconductors N.V. and Beijing JianGuang Asset Management Co. Ltd established Bipolar Power joint venture (JV), **WeEn Semiconductors**, which will be used in future Bipolar Power documents together with new contact details.

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Thank you for your cooperation and understanding,

WeEn Semiconductors





BT151S-650S

SCR

20 June 2014

Product data sheet

1. General description

Passivated sensitive gate Silicon Controlled Rectifier (SCR) in a SOT428 (DPAK) surface mountable plastic package intended for use in applications requiring high bidirectional blocking voltage capability and high thermal cycling performance. These devices are intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

2. Features and benefits

- Direct interfacing with low power drivers and microcontrollers
- High bidirectional blocking voltage capability
- High thermal cycling performance
- Planar passivated for voltage ruggedness and reliability
- Surface mountable package
- Sensitive gate for logic level control

3. Applications

- General purpose switching and phase control
- Ignition circuits, CDI for 2- and 3-wheelers
- Motor control - e.g. small kitchen appliances
- Protection circuits for Switched-Mode Power Supplies (SMPS)
- Protection circuits in lighting ballasts

4. Quick reference data

Table 1. Quick reference data

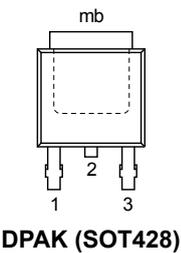
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	-	650	V
V_{RRM}	repetitive peak reverse voltage		-	-	650	V
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5	-	-	90	A
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 100\text{ °C}$; Fig. 1	-	-	7.5	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 100\text{ °C}$; Fig. 2 ; Fig. 3	-	-	12	A



Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 8	20	50	200	μA

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p style="text-align: center;">DPAK (SOT428)</p>	 <p style="text-align: center;">sym037</p>
2	A	anode		
3	G	gate		
mb	A	mounting base; connected to anode		

6. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
BT151S-650S	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	SOT428

7. Marking

Table 4. Marking codes

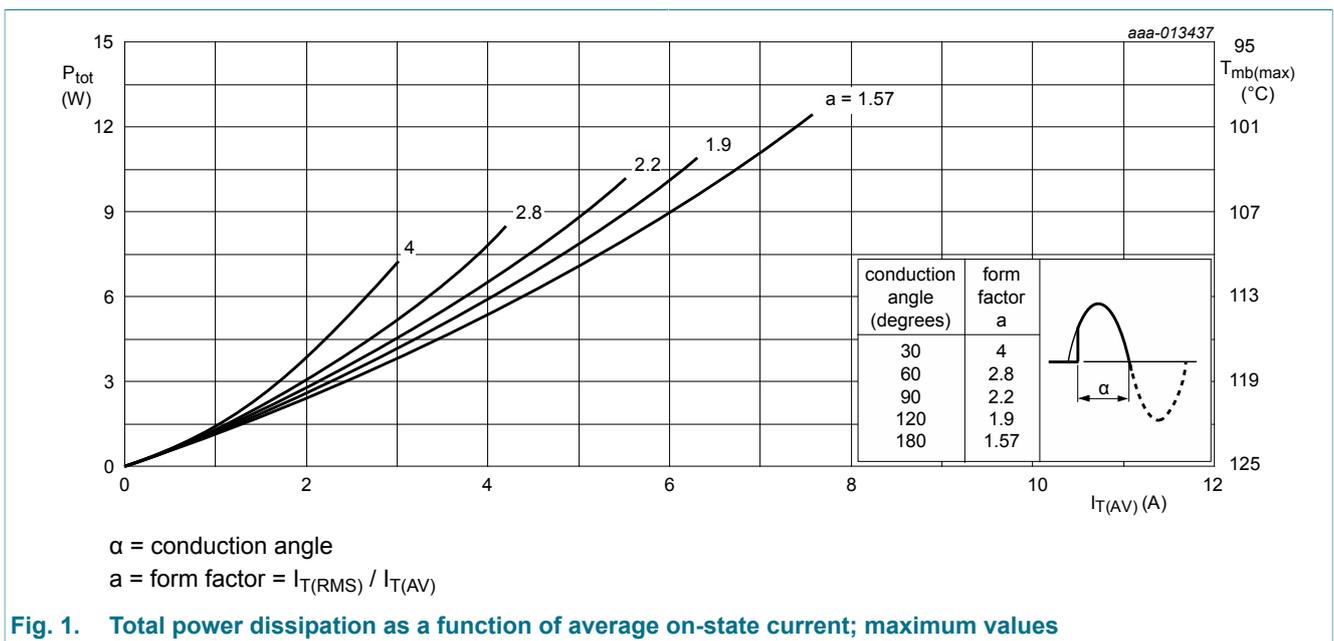
Type number	Marking code
BT151S-650S	BT151S-650S

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	650	V
V_{RRM}	repetitive peak reverse voltage		-	650	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 100\text{ }^\circ\text{C}$; Fig. 1	-	7.5	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 100\text{ }^\circ\text{C}$; Fig. 2 ; Fig. 3	-	12	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5	-	90	A
		half sine wave; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; $t_p = 8.3\text{ ms}$	-	100	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; SIN	-	41	A^2s
di_T/dt	rate of rise of on-state current	$I_T = 20\text{ A}$; $I_G = 50\text{ mA}$; $dI_G/dt = 50\text{ mA}/\mu\text{s}$	-	50	$\text{A}/\mu\text{s}$
I_{GM}	peak gate current		-	2	A
V_{RGM}	peak reverse gate voltage		-	5	V
P_{GM}	peak gate power		-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.5	W
T_{stg}	storage temperature		-40	150	$^\circ\text{C}$
T_j	junction temperature		-	125	$^\circ\text{C}$



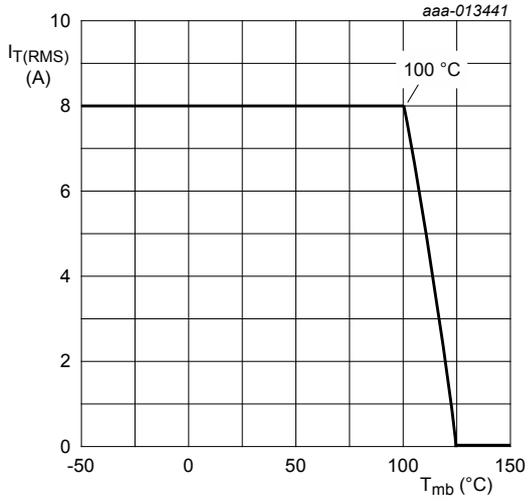
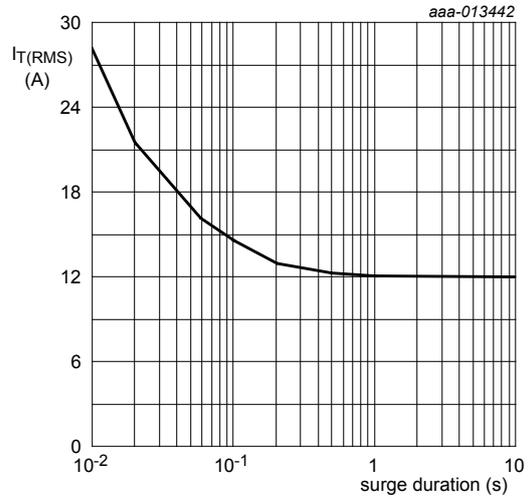
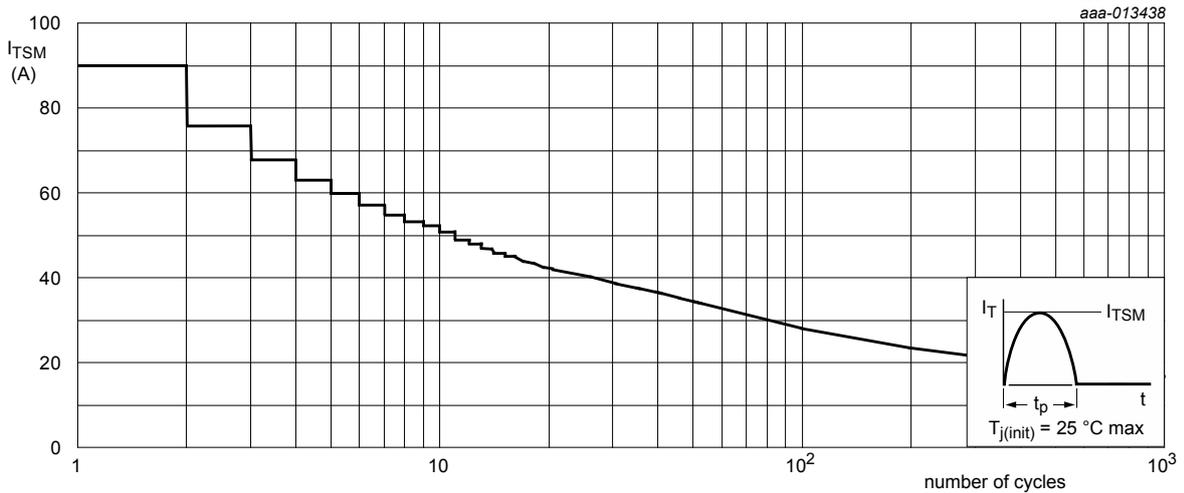


Fig. 2. RMS on-state current as a function of mounting base temperature; maximum values



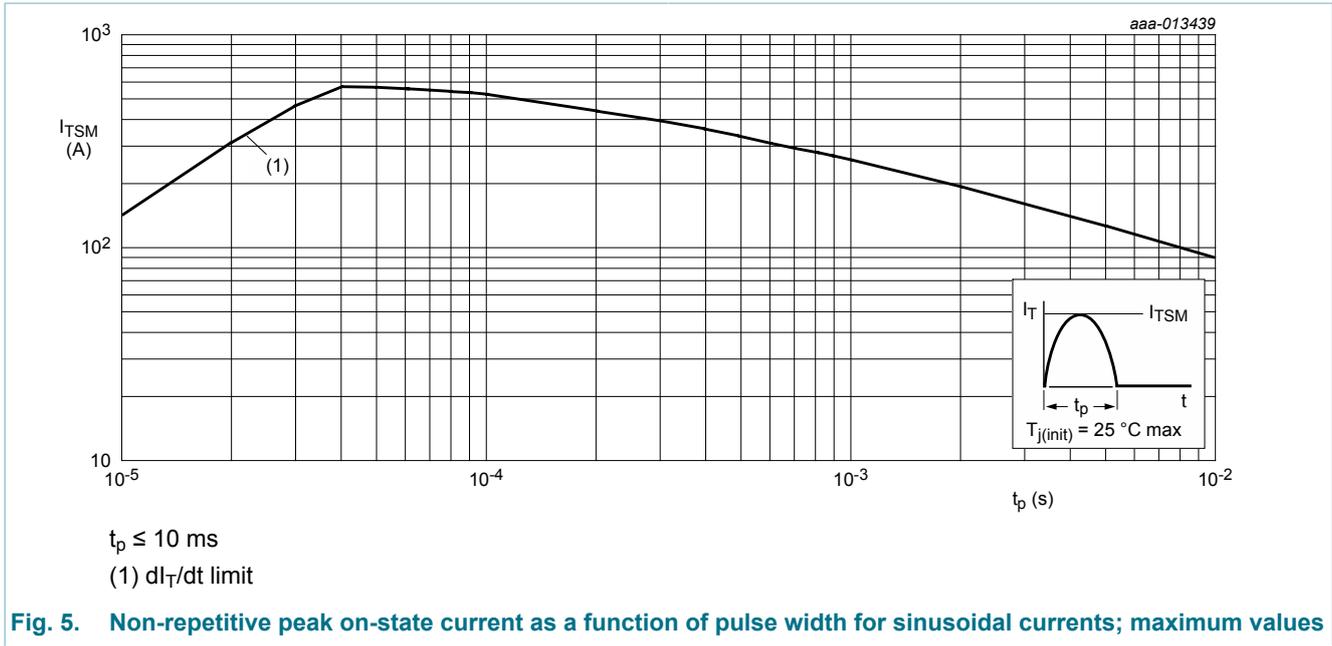
f = 50 Hz; $T_{mb} = 100\text{ °C}$

Fig. 3. RMS on-state current as a function of surge duration; maximum values



f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 6	-	-	2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	Device mounted on an FR4 printed-circuit board, single-sided copper, tin-plated and standard footprint; Fig. 7	-	7	-	K/W

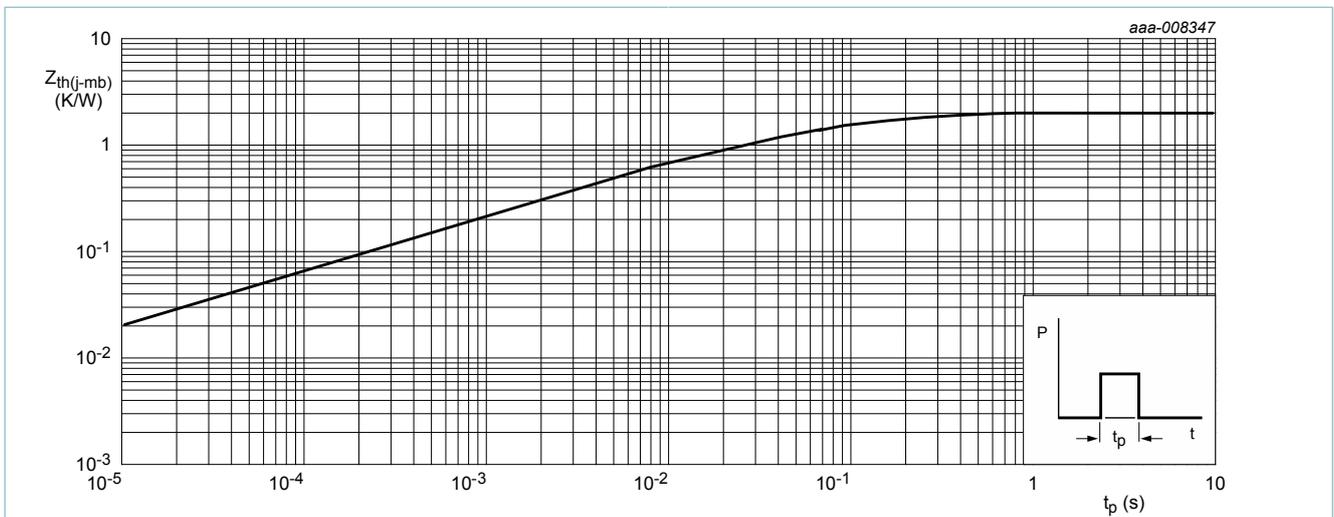


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse width

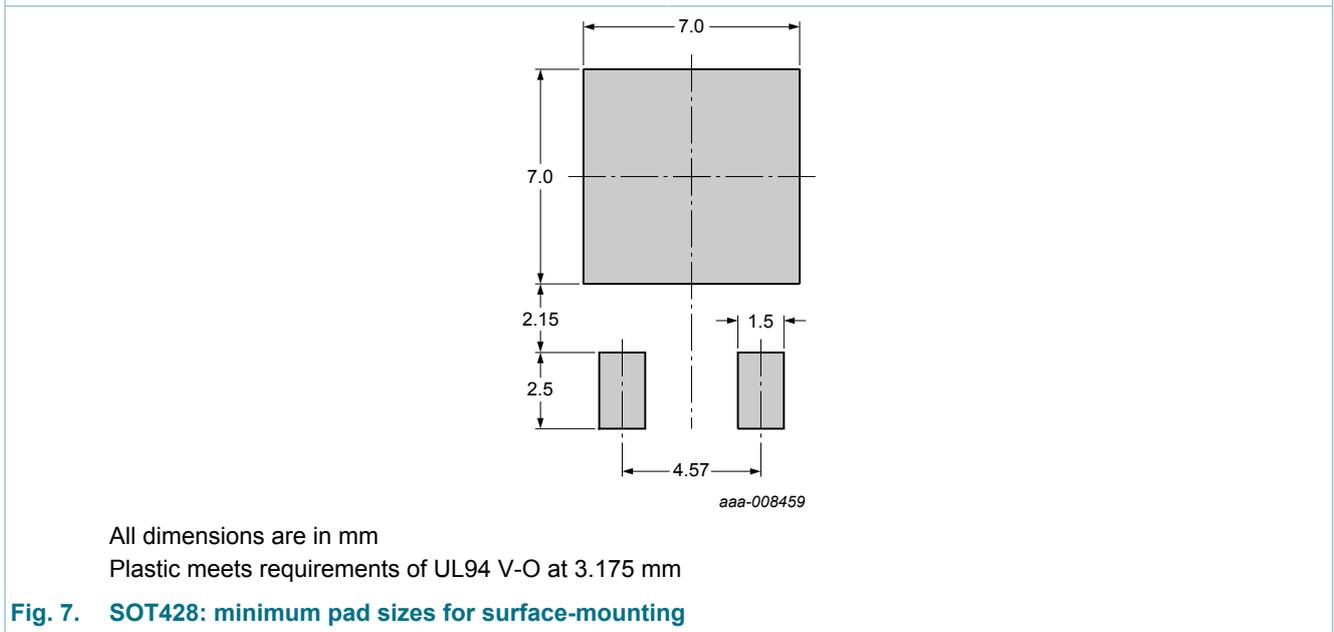
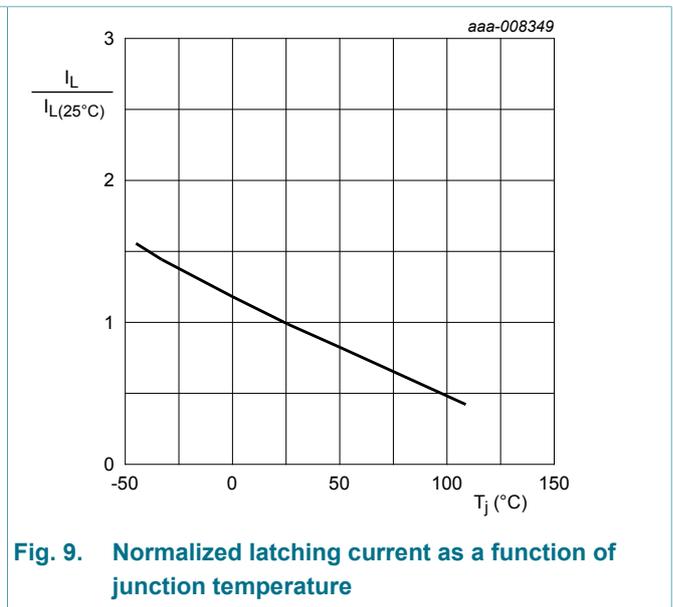
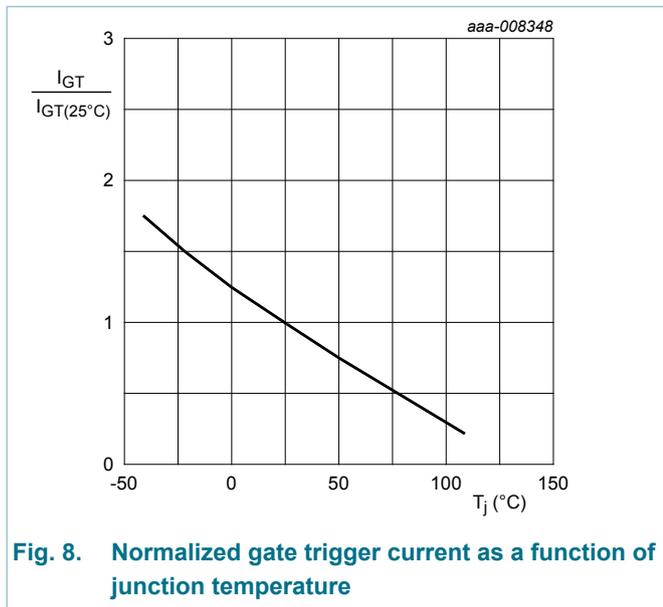


Fig. 7. SOT428: minimum pad sizes for surface-mounting

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ }^\circ\text{C}$; Fig. 8	20	50	200	μA
I_L	latching current	$V_D = 12\text{ V}$; $I_G = 0.1\text{ A}$; $T_j = 25\text{ }^\circ\text{C}$; Fig. 9	-	0.4	10	mA
I_H	holding current	$V_D = 12\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$; Fig. 10	-	0.3	6	mA
V_T	on-state voltage	$I_T = 20\text{ A}$; $T_j = 25\text{ }^\circ\text{C}$; Fig. 11	-	1.3	1.75	V
V_{GT}	gate trigger voltage	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ }^\circ\text{C}$; Fig. 12	-	0.6	1	V
		$V_D = 650\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 110\text{ }^\circ\text{C}$; Fig. 12	0.1	0.2	-	V
I_D	off-state current	$V_D = 650\text{ V}$; $T_j = 125\text{ }^\circ\text{C}$	-	0.1	0.5	mA
I_R	reverse current	$V_R = 650\text{ V}$; $T_j = 125\text{ }^\circ\text{C}$	-	0.1	0.5	mA
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 436\text{ V}$; $T_j = 125\text{ }^\circ\text{C}$; $R_{GK} = 100\text{ }\Omega$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; Fig. 13	50	100	-	V/ μs



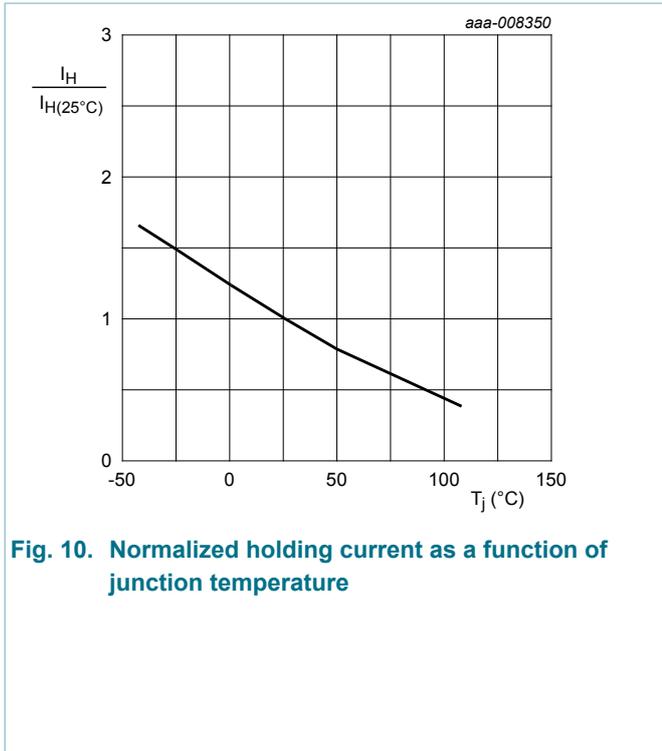


Fig. 10. Normalized holding current as a function of junction temperature

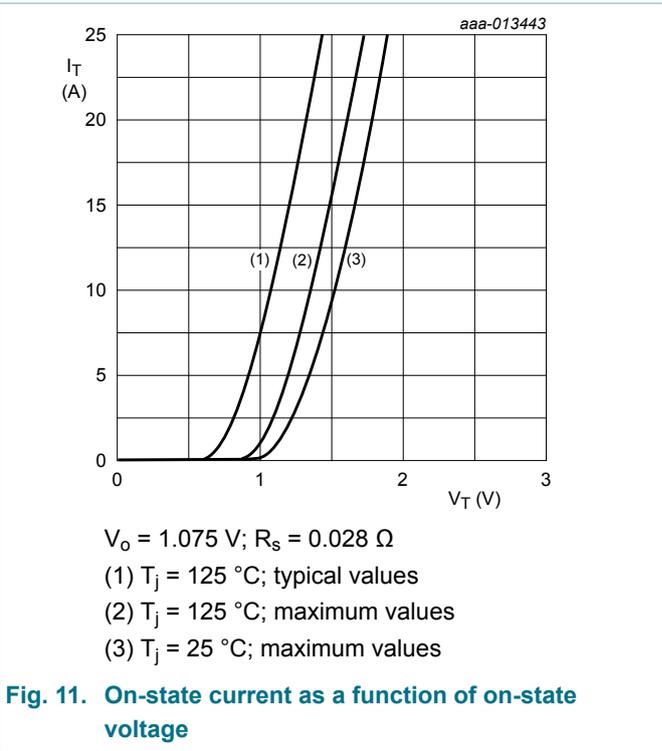


Fig. 11. On-state current as a function of on-state voltage

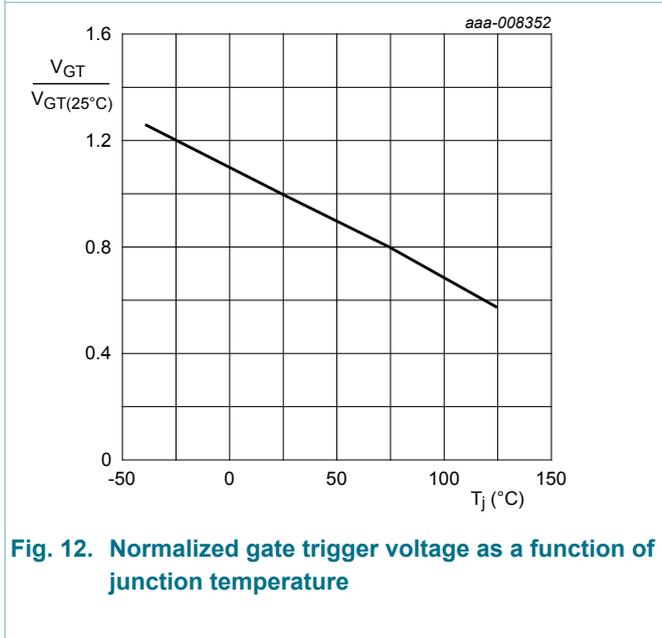


Fig. 12. Normalized gate trigger voltage as a function of junction temperature

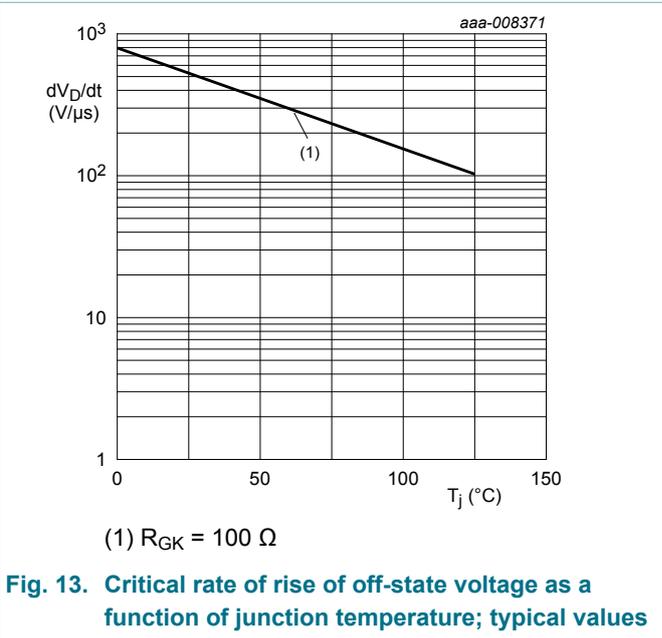
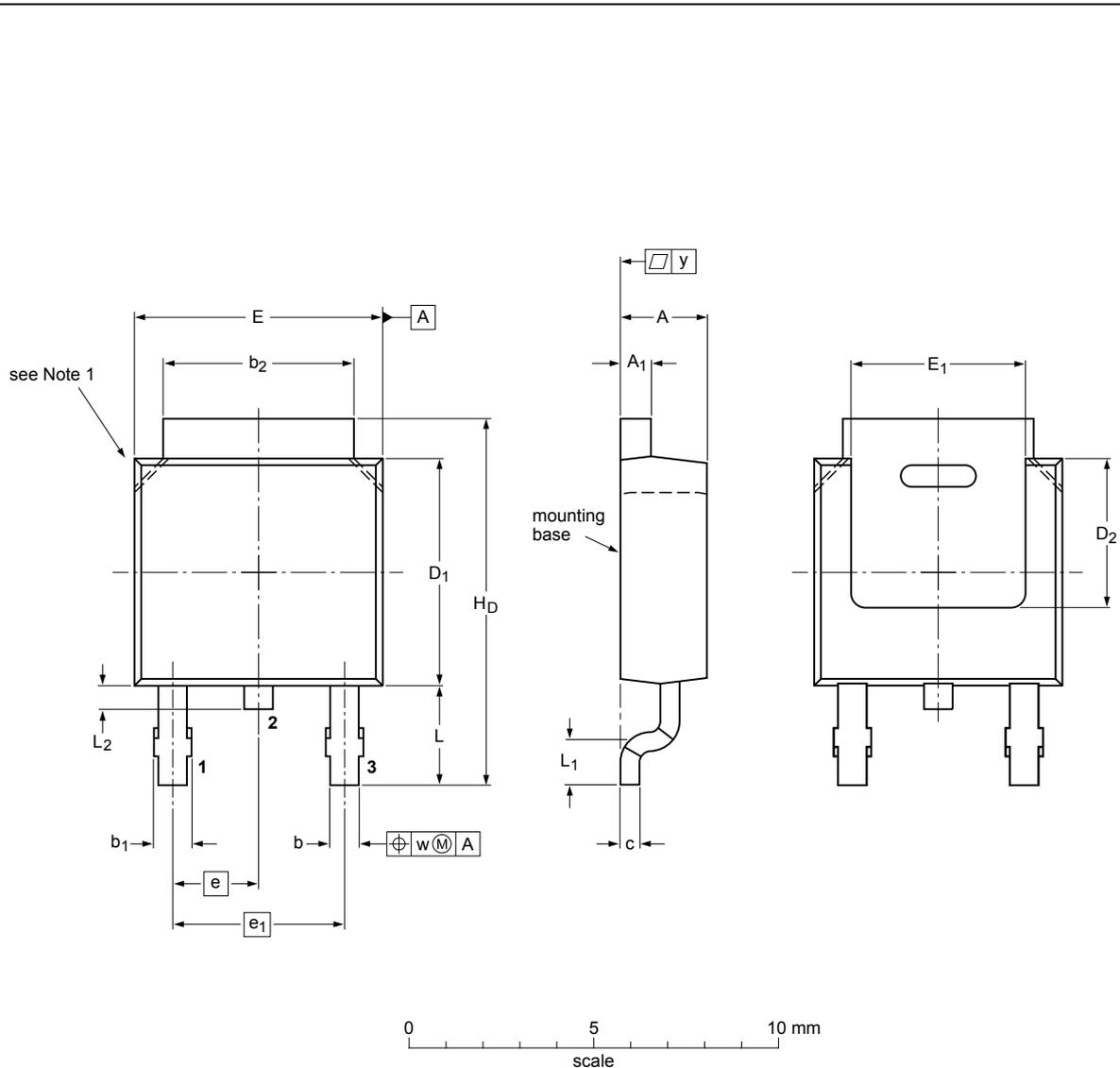


Fig. 13. Critical rate of rise of off-state voltage as a function of junction temperature; typical values

11. Package outline

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) SOT428



Dimensions (mm are the original dimensions)

Unit	A	A ₁	b	b ₁	b ₂	c	D ₁	D ₂	E	E ₁	e	e ₁	H _D	L	L ₁	L ₂	w	y
max	2.38	0.93	0.89	1.1	5.46	0.56	6.22		6.73				10.4	2.95		0.9		0.2
nom											2.285	4.57					0.2	
min	2.22	0.46	0.71	0.9	5.00	0.20	5.98	4.0	6.47	4.45			9.6	2.55	0.5	0.5		

Note

1. Plastic body may have 45° chamfer.

sot428_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT428		TO-252	SC-63		06-03-16 14-06-10

Fig. 14. Package outline DPAK (SOT428)

12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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